

2.1 General Precautions Regarding Semiconductor Devices

⚠CAUTION

Do not use devices under conditions exceeding their absolute maximum ratings (e.g. current, voltage, power dissipation or temperature).

This may cause the device to break down, may degrade its performance, or cause it to catch fire or explode, resulting in injury.

Do not insert devices in the wrong orientation.

Make sure that the positive and negative terminals of power supplies are connected correctly. Otherwise, the rated maximum current or power dissipation may be exceeded and the device may break down or undergo performance degradation, causing it to catch fire or explode and resulting in injury.

When power to a device is on, do not touch the device's heat sink.

Heat sinks become hot, so you may burn your hand.

Do not touch the tips of device leads.

Because some types of device have leads with pointed tips, you may prick your finger.

When conducting any kind of evaluation, inspection or testing, be sure to connect the testing equipment's electrodes or probes to the pins of the device under test before powering it on.

Otherwise, you may receive an electric shock, causing injury.

Before grounding an item of measuring equipment or a soldering iron, check that there is no electrical leakage from it.

Electrical leakage may cause the device which you are testing or soldering to break down, or could give you an electric shock.

Always wear protective glasses when cutting the leads of a device with clippers or a similar tool.

If you do not, small bits of metal flying off the cut ends may damage your eyes.